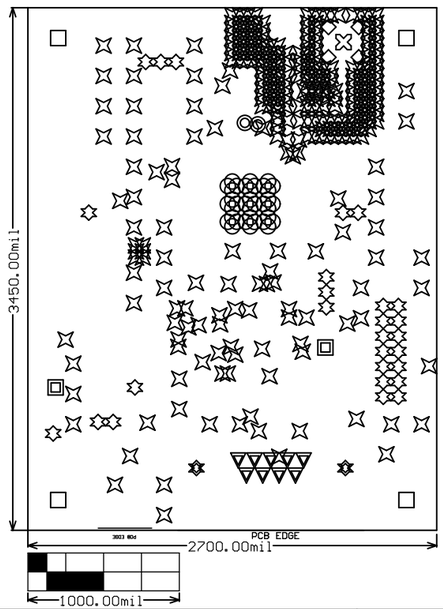
FABRICATION NOTES

1. Top Layer contains 90 ohm differential using 8.5 mil trace and 5 mil spacing.
2. Top Layer contains 50 ohm controlled impedance using 18 mil trace.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4 High TG	10.00mil	4.2	
5	Signal Layer 1	Copper	1.40mil		
6	Dielectric 3	FR-4 High TG	36.00mil	4.2	
7	Signal Layer 2	Copper	1.40mil		
8	Dielectric 2	FR-4 High TG	10.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	36	7.87mil (0.200mm)	PTH	Round
⊠	294	12.00mil (0.305mm)	PTH	Round
◉	2	16.00mil (0.406mm)	PTH	Round
▼	9	39.37mil (1.000mm)	PTH	Round
✡	27	40.00mil (1.016mm)	PTH	Round
⊠	1	59.06mil (1.500mm)	PTH	Round
◇	4	62.99mil (1.600mm)	PTH	Round
◘	2	63.00mil (1.600mm)	PTH	Round
✱	2	122.05mil (3.100mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
	381 Total			

DESIGN INFORMATION

MIN. TRACK WIDTH: 8.5 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER _____
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: CAN to Wi-Fi Gateway
DESIGNED FOR: Public Release
FILE NAME: ISE4040_TIDA00380_CANtoWiFi.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4040	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: TIDA-00380		
PLOT NAME = Fabrication Drawing	GENERATED : 9/22/2015 10:26:52 AM	TEXAS INSTRUMENTS	

ENGINEER: M. Knapp	LAYOUT BY: Krypton Solution LLC
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.18.45973

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